

**Analog Output MEMS Microphone Flex Evaluation Board User Guide**

**GENERAL DESCRIPTION**

This user guide applies to the following MEMS microphone evaluation boards:

- EV\_INMP404-FX
- EV\_INMP405-FX
- EV\_INMP504-FX
- EV\_INMP510-FX
- EV\_ICS-40180-FX
- EV\_ICS-40181-FX
- EV\_ICS-40310-FX

This is a simple evaluation board that allows quick evaluation of the performance of single-ended analog MEMS microphones. The small size and low profile of the flexible PCB enables direct placement of the microphone into a prototype or an existing design for an in situ evaluation. The evaluation board consists of a bottom port microphone soldered to a flexible PCB with color-coded wires attached. The only other component on the board is a 0.1  $\mu$ F supply bypass capacitor.

Table 1 describes the functions of the three connection wires. Table 2 describes the functional differences between the different microphones that are used with this flex circuit.

**TABLE 1. PIN FUNCTION DESCRIPTIONS**

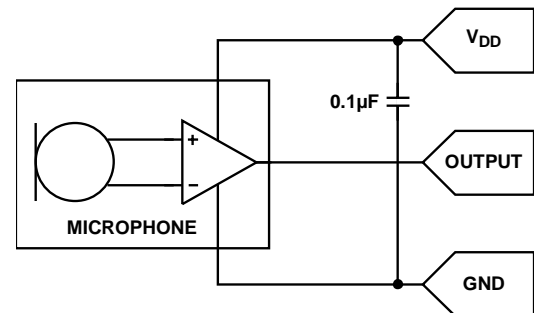
Wire Color	Microphone Pin	Description
Red	VDD	Power Supply. 1.5 V DC to 3.6 V DC; (0.9 V DC to 1.3 V DC for ICS-40310)
White	OUTPUT	Analog Output Signal
Black	GND	Ground

**TABLE 2. MICROPHONE FUNCTIONAL DIFFERENCES**

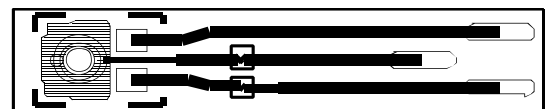
Microphone	Maximum Supply Current	Maximum Output Voltage	Output Impedance	DC Offset
INMP404	250 $\mu$ A	0.18 V rms	200 $\Omega$	0.8 V
INMP405	250 $\mu$ A	0.18 V rms	200 $\Omega$	0.8 V
INMP504	225 $\mu$ A	0.18 V rms	200 $\Omega$	0.8 V
INMP510	250 $\mu$ A	0.40 V rms	350 $\Omega$	0.7 V
ICS-40180	260 $\mu$ A	0.40 V rms	350 $\Omega$	0.7 V
ICS-40181	250 $\mu$ A	0.40 V rms	350 $\Omega$	0.7 V
ICS-40310	25 $\mu$ A	0.12 V rms	4.5 k $\Omega$	0.57 V

**EVALUATION BOARD CIRCUIT**

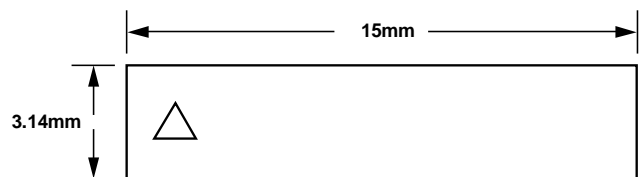
Figure 1 shows the schematic of the evaluation board, and Figure 2 shows the flex board layout. See the respective microphone data sheets for complete descriptions and specifications of the microphones. Note that the layout for the EV\_ICS-40181-FX differs slightly from what is shown in Figure 2 because of this part’s different package footprint, but the routing of the three signals is consistent.



**Figure 1. Evaluation Board Schematic**

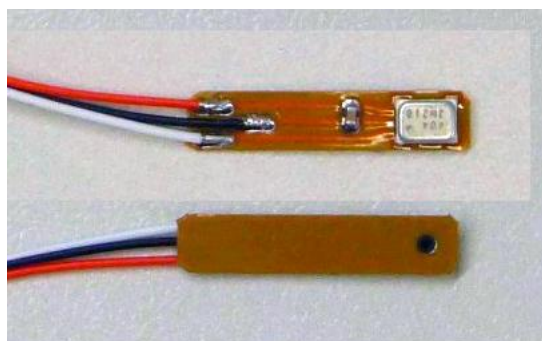


**Figure 2. Evaluation Board Layout (Top View)**



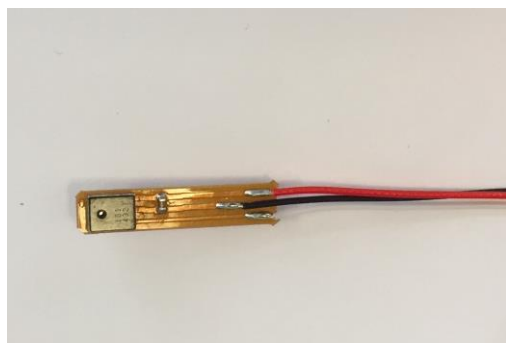
**Figure 3. Evaluation Board Dimensions in Millimeters (Wires Not Included)**

**BOTTOM PORT EVALUATION BOARD PHOTOGRAPH**



**Figure 4. Top and Bottom View**

**TOP PORT EVALUATION BOARD PHOTOGRAPH**



**Figure 5. Top View**

**REVISION HISTORY**

REVISION DATE	REVISION	DESCRIPTION
10/14/2015	1.3	This v1.3 is the initial release in Agile. Previous revisions were uncontrolled.
03/26/2015	1.4	Updated part names, added Figure 5

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